

## 低噪声、低静态电流、高精度运算放大器 **e-trim™** 系列

 查询样品: [OPA376-Q1](#), [OPA2376-Q1](#), [OPA4376-Q1](#)

### 特性

- 符合汽车应用要求
- 低噪声: **1kHz** 下为  **$7.5\text{nV}/\sqrt{\text{Hz}}$**
- **0.1 Hz 至 10 Hz** 噪声:  **$0.8\mu\text{V}_{\text{PP}}$**
- 静态电流:  **$760\mu\text{V}$**  (典型值)
- 低偏移电压:  **$5\mu\text{V}$**  (典型值)
- 增益带宽产品: **5.5MHz**
- 轨至轨输出
- 单电源供电
- 电源电压: **2.2 V 至 5.5V**
- 小型封装:
  - **SC-70, SOT23, MSOP, TSSOP**

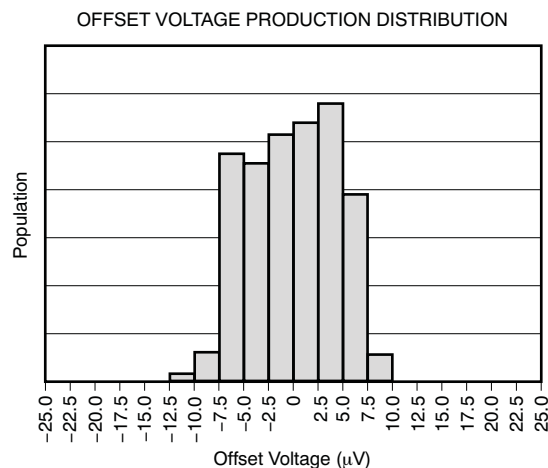
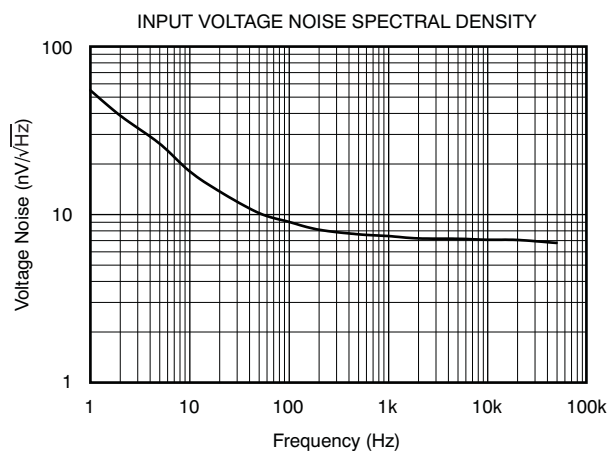
### 应用

- **ADC** 缓冲器
- 音频设备
- 医疗仪表
- 手持测试设备
- 有源滤波
- 传感器信号调节

### 说明

OPA376-Q1系列是支持 **e-trim** 的新一代低噪声运算放大器, 可提供极高的 **dc** 精度与 **ac** 性能。轨至轨输出、低失调 ( **$25\mu\text{V}$**  最大值)、低噪声 ( **$7.5\text{nV}/\sqrt{\text{Hz}}$** )、 **$950\mu\text{A}$**  的最大静态电流以及 **5.5 MHz** 带宽使该部件非常适用于各种不同的高精度便携式应用。此外, 该器件还具有支持出色 **PSRR** 的宽泛电源, 理想适用于直接通过电池运行而无稳压的应用。

OPA376-Q1 (单通道) 采用 **MicroSIZE** SC70-5、SOT23-5 与 SO-8 封装。OPA2376-Q1 (双通道) 采用 SO-8 封装。OPA4376-Q1 (四通道) 采用 TSSOP-14 封装。所有器件版本的特定工作温度范围均为  **$-40^{\circ}\text{C}$  至  $125^{\circ}\text{C}$**



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English Data Sheet: [SBOS549](#)



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### ABSOLUTE MAXIMUM RATING<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		VALUE	UNIT
Supply voltage	$V_S = (V+) - (V-)$	+7	V
Signal input terminals	Voltage <sup>(2)</sup>	$(V-) - 0.5$ to $(V+) + 0.5$	V
	Current <sup>(2)</sup>	±10	mA
Output short-circuit <sup>(3)</sup>		Continuous	
Operating temperature	$T_A$	-40 to +125	°C
Storage temperature	$T_A$	-65 to +150	°C
Junction temperature	$T_J$	+150	°C

- (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not supported.
- (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less.
- (3) Short-circuit to ground, one amplifier per package.

### PACKAGE INFORMATION<sup>(1)</sup>

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	PACKAGE MARKING
OPA376-Q1	SC70-5	DCK	Preview
	SOT23-5	DBV	OUHQ
	SO-8	D	Preview
OPA2376-Q1	SO-8	D	Preview
	MSOP-8	DGK	Preview
OPA4376-Q1	TSSOP-14	PW	Preview

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or visit the device product folder at [www.ti.com](http://www.ti.com).

**ELECTRICAL CHARACTERISTICS:  $V_S = +2.2V$  to  $+5.5V$** 
**Boldface** limits apply over the specified temperature range:  $T_A = -40^{\circ}C$  to  $+125^{\circ}C$ .

At  $T_A = +25^{\circ}C$ ,  $R_L = 10k\Omega$  connected to  $V_S/2$ ,  $V_{CM} = V_S/2$ , and  $V_{O_{UT}} = V_S/2$ , unless otherwise noted.

PARAMETERS	CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFFSET VOLTAGE</b>					
Input Offset Voltage	$V_{OS}$		5	25	$\mu V$
vs Temperature	$dV_{OS}/dT$	$-40^{\circ}C$ to $+85^{\circ}C$	0.26	1	$\mu V/^{\circ}C$
		<b><math>-40^{\circ}C</math> to <math>+125^{\circ}C</math></b>	<b>0.32</b>	<b>2</b>	<b><math>\mu V/^{\circ}C</math></b>
vs Power Supply	PSRR	$V_S = +2.2V$ to $+5.5V$ , $V_{CM} < (V+) - 1.3V$	5	20	$\mu V/V$
<b>Over Temperature</b>		<b><math>V_S = +2.2V</math> to <math>+5.5V</math>, <math>V_{CM} &lt; (V+) - 1.3V</math></b>	<b>5</b>		<b><math>\mu V/V</math></b>
Channel Separation, dc (dual, quad)			0.5		mV/V
<b>INPUT BIAS CURRENT</b>					
Input Bias Current	$I_B$		0.2	10	pA
<b>Over Temperature</b>			See <a href="#">Typical Characteristics</a>		<b>pA</b>
Input Offset Current	$I_{OS}$		0.2	10	pA
<b>NOISE</b>					
Input Voltage Noise, $f = 0.1Hz$ to $10Hz$			0.8		$\mu V_{PP}$
Input Voltage Noise Density, $f = 1kHz$	$e_n$		7.5		$nV/\sqrt{Hz}$
Input Current Noise, $f = 1kHz$	$i_n$		2		$fA/\sqrt{Hz}$
<b>INPUT VOLTAGE RANGE</b>					
Common-Mode Voltage Range	$V_{CM}$	$(V-) - 0.1$		$(V+) + 0.1$	V
Common-Mode Rejection Ratio	CMRR	$(V-) < V_{CM} < (V+) - 1.3V$	76	90	dB
<b>INPUT CAPACITANCE</b>					
Differential			6.5		pF
Common-Mode			13		pF
<b>OPEN-LOOP GAIN</b>					
Open-Loop Voltage Gain	$A_{OL}$	$50mV < V_O < (V+) - 50mV$ , $R_L = 10k\Omega$	120	134	dB
		$100mV < V_O < (V+) - 100mV$ , $R_L = 2k\Omega$	120	126	dB
<b>FREQUENCY RESPONSE</b> $C_L = 100pF$ , $V_S = 5.5V$					
Gain-Bandwidth Product	GBW		5.5		MHz
Slew Rate	SR	$G = +1$	2		V/ $\mu s$
Settling Time 0.1%	$t_s$	2V Step, $G = +1$	1.6		$\mu s$
Settling Time 0.01%	$t_s$	2V Step, $G = +1$	2		$\mu s$
Overload Recovery Time		$V_{IN} \times Gain > V_S$	0.33		$\mu s$
THD + Noise	THD+N	$V_O = 1V_{RMS}$ , $G = +1$ , $f = 1kHz$ , $R_L = 10k\Omega$	0.00027		%
<b>OUTPUT</b>					
Voltage Output Swing from Rail		$R_L = 10k\Omega^{(1)}$	10	20	mV
		$R_L = 10k\Omega^{(2)}$	20	30	mV
<b>Over Temperature</b>		<b><math>R_L = 10k\Omega</math></b>		<b>40</b>	<b>mV</b>
Voltage Output Swing from Rail		$R_L = 2k\Omega^{(1)}$	40	50	mV
		$R_L = 2k\Omega^{(2)}$	50	60	mV
<b>Over Temperature</b>		<b><math>R_L = 2k\Omega</math></b>		<b>80</b>	<b>mV</b>
Short-Circuit Current	$I_{SC}$		+30/-50		mA
Capacitive Load Drive	$C_{LOAD}$		See <a href="#">Typical Characteristics</a>		
Open-Loop Output Impedance	$R_O$		150		$\Omega$

(1) SC70-5, SOT23-5, SO-8, MSOP-8, and TSSOP-14 packages only.

(2) Wafer chip-scale package only.

**ELECTRICAL CHARACTERISTICS:  $V_S = +2.2V$  to  $+5.5V$  (continued)**

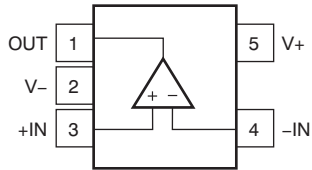
**Boldface** limits apply over the specified temperature range:  $T_A = -40^{\circ}C$  to  $+125^{\circ}C$ .

At  $T_A = +25^{\circ}C$ ,  $R_L = 10k\Omega$  connected to  $V_S/2$ ,  $V_{CM} = V_S/2$ , and  $V_{O UT} = V_S/2$ , unless otherwise noted.

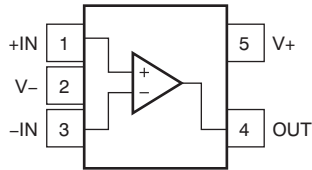
PARAMETERS	CONDITIONS	MIN	TYP	MAX	UNIT
<b>POWER SUPPLY</b>					
Specified Voltage Range	$V_S$	2.2		5.5	V
Operating Voltage Range			2 to 5.5		V
Quiescent Current per amplifier	$I_Q$ $I_O = 0, V_S = +5.5V, V_{CM} < (V+) - 1.3V$		760	950	$\mu A$
<b>Over Temperature</b>				<b>1</b>	<b>mA</b>
<b>TEMPERATURE RANGE</b>					
Specified Range		-40		+125	$^{\circ}C$
Operating Range		-40		+150	$^{\circ}C$
Thermal Resistance	$\theta_{JA}$				$^{\circ}C/W$
SC70			250		$^{\circ}C/W$
SOT23			200		$^{\circ}C/W$
SO-8, TSSOP-14, MSOP-8			150		$^{\circ}C/W$

PIN CONFIGURATIONS

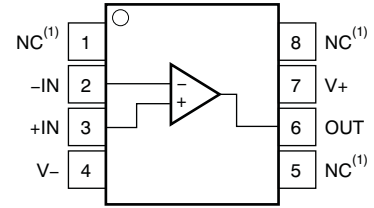
OPA376-Q1  
SOT23-5  
(TOP VIEW)



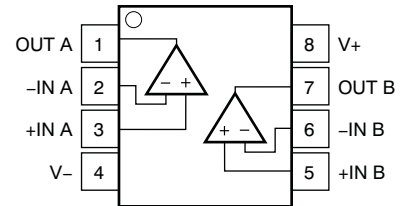
OPA376-Q1  
SC70-5  
(TOP VIEW)



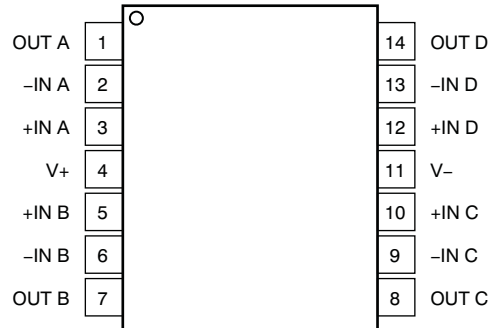
OPA376-Q1  
SO-8  
(TOP VIEW)



OPA2376-Q1  
SO-8, MSOP-8  
(TOP VIEW)



OPA4376-Q1  
TSSOP-14  
(TOP VIEW)



NOTE: (1) NC denotes no internal connection.

### TYPICAL CHARACTERISTICS

At  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ ,  $R_L = 10\text{k}\Omega$  connected to  $V_S/2$ ,  $V_{CM} = V_S/2$ , and  $V_{OUT} = V_S/2$ , unless otherwise noted.

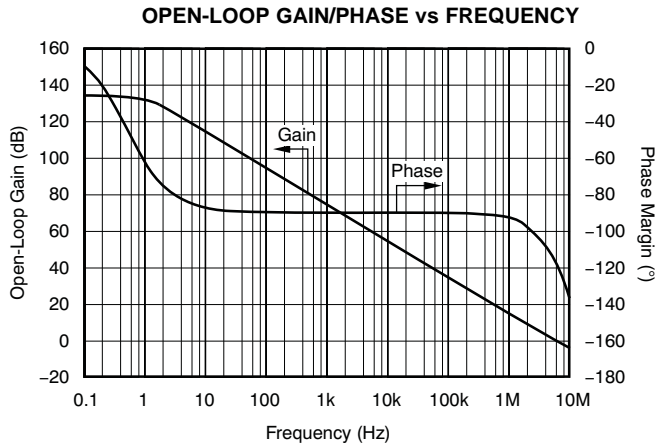


Figure 1.

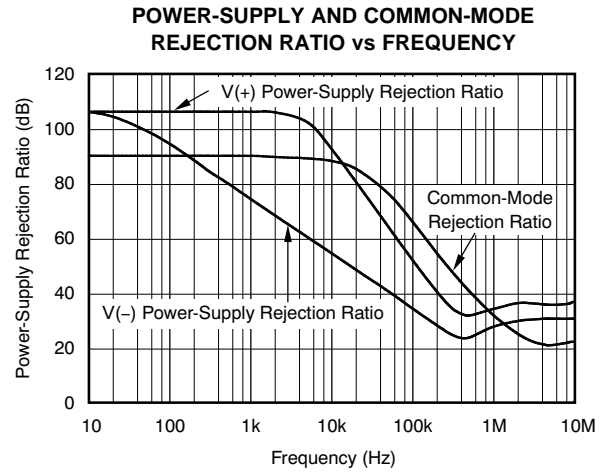


Figure 2.

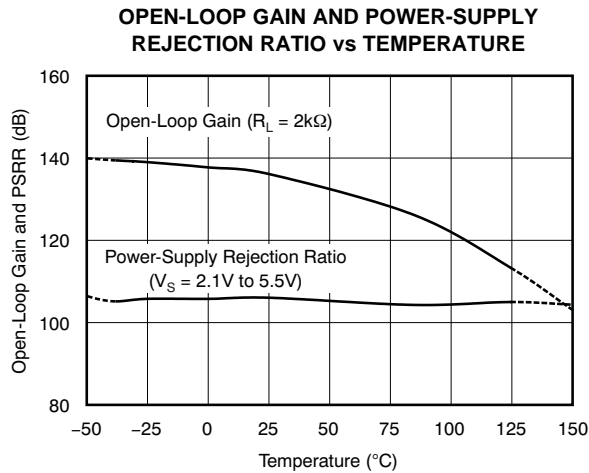


Figure 3.

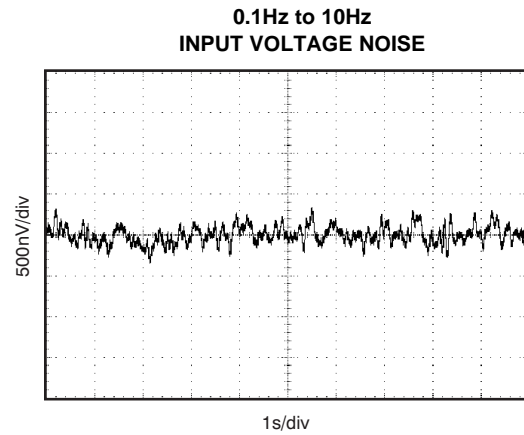


Figure 4.

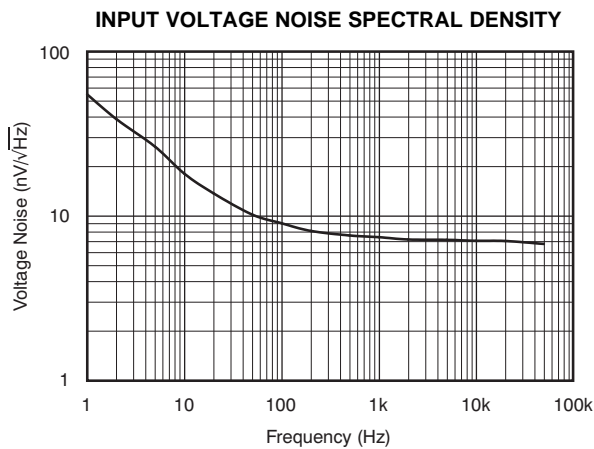


Figure 5.

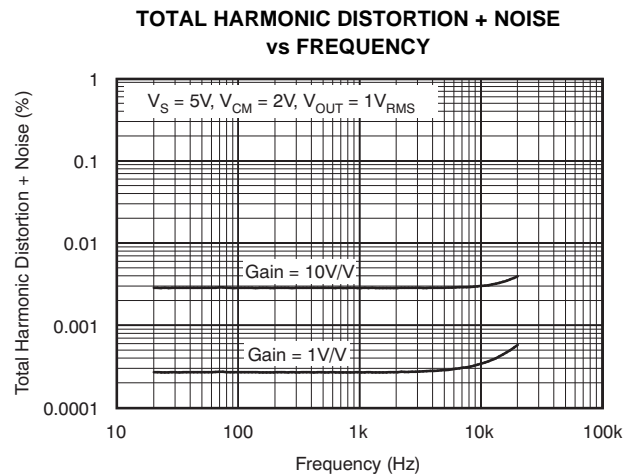


Figure 6.

**TYPICAL CHARACTERISTICS (continued)**

At  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ ,  $R_L = 10\text{k}\Omega$  connected to  $V_S/2$ ,  $V_{CM} = V_S/2$ , and  $V_{OUT} = V_S/2$ , unless otherwise noted.

**COMMON-MODE REJECTION RATIO vs TEMPERATURE**

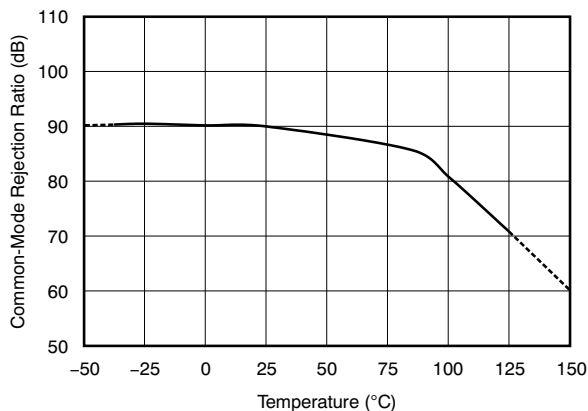


Figure 7.

**QUIESCENT CURRENT vs TEMPERATURE**

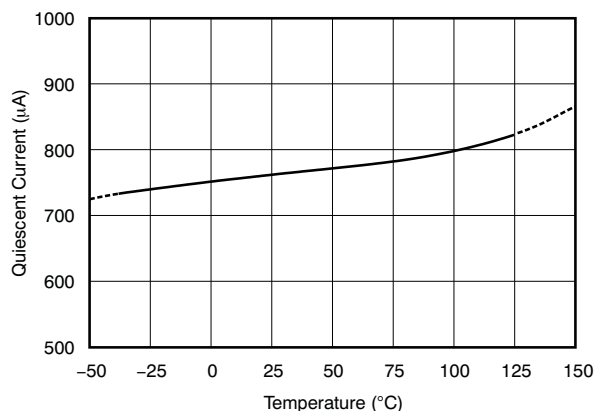


Figure 8.

**QUIESCENT AND SHORT-CIRCUIT CURRENT vs SUPPLY VOLTAGE**

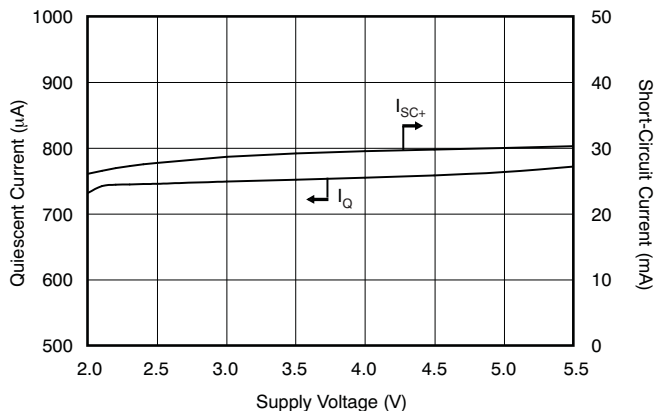


Figure 9.

**SHORT-CIRCUIT CURRENT vs TEMPERATURE**

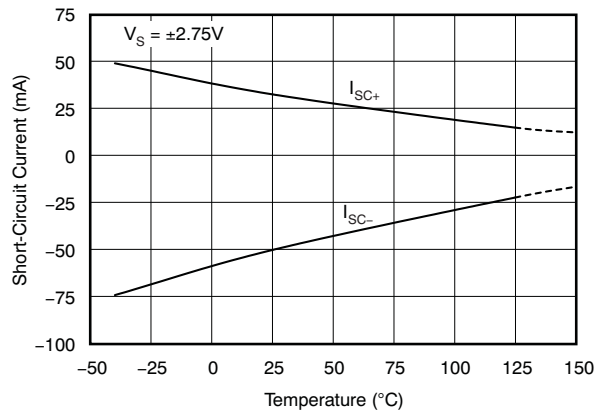


Figure 10.

**INPUT BIAS CURRENT vs TEMPERATURE**

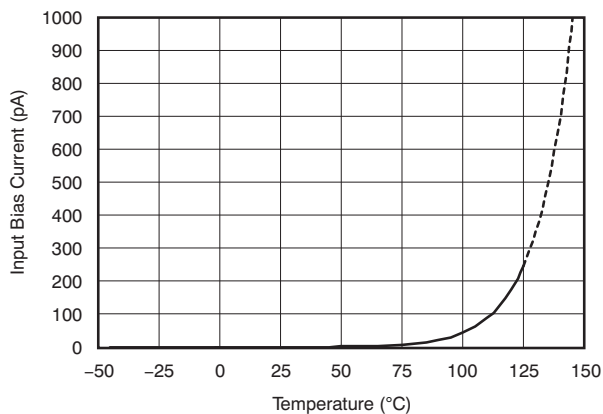


Figure 11.

**OUTPUT VOLTAGE vs OUTPUT CURRENT**

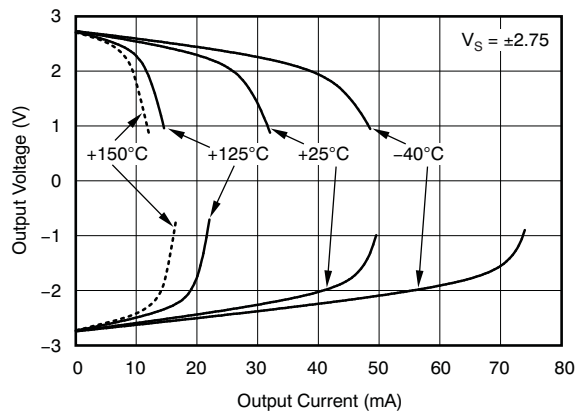


Figure 12.

**TYPICAL CHARACTERISTICS (continued)**

At  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ ,  $R_L = 10\text{k}\Omega$  connected to  $V_S/2$ ,  $V_{CM} = V_S/2$ , and  $V_{O\text{UT}} = V_S/2$ , unless otherwise noted.

**OFFSET VOLTAGE  
 PRODUCTION DISTRIBUTION**

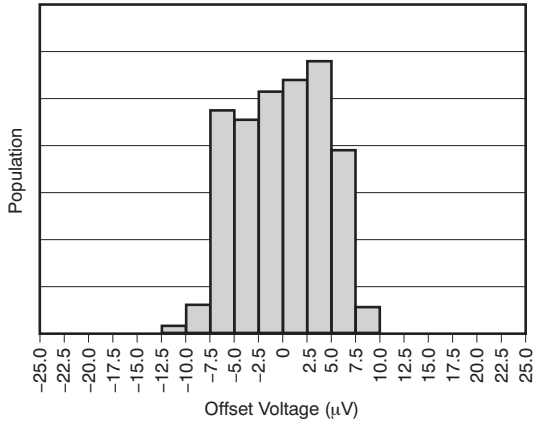


Figure 13.

**OFFSET VOLTAGE DRIFT  
 PRODUCTION DISTRIBUTION  
 (-40°C to +125°C)**

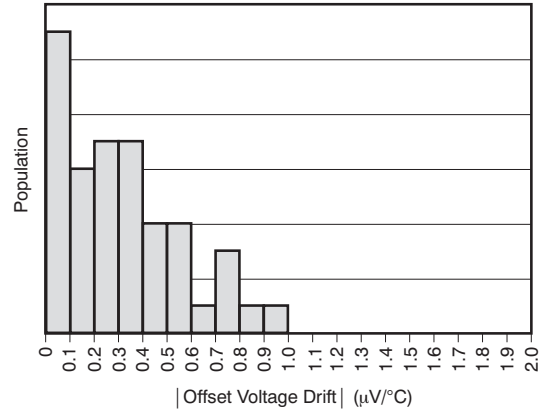


Figure 14.

**MAXIMUM OUTPUT VOLTAGE vs FREQUENCY**

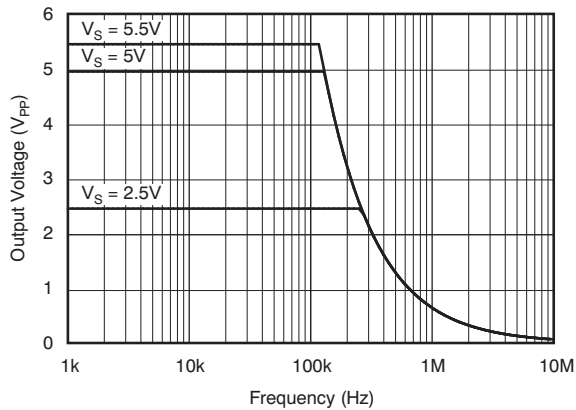


Figure 15.

**SMALL-SIGNAL OVERSHOOT vs LOAD CAPACITANCE**

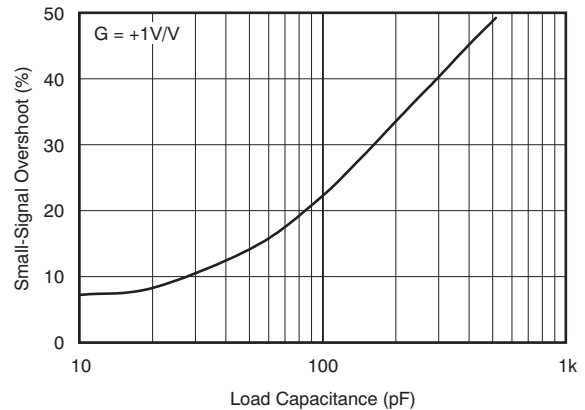


Figure 16.

**SMALL-SIGNAL PULSE RESPONSE**

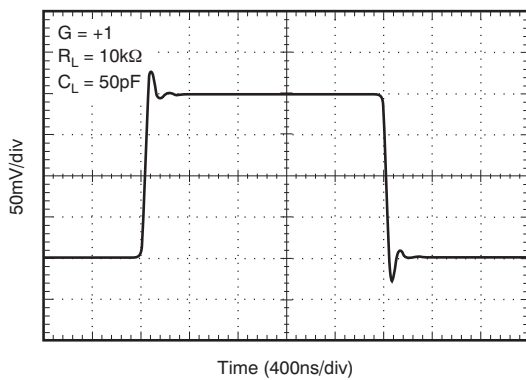


Figure 17.

**LARGE-SIGNAL PULSE RESPONSE**

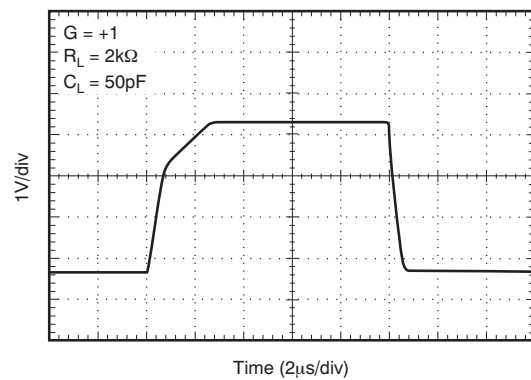


Figure 18.



**TYPICAL CHARACTERISTICS (continued)**

At  $T_A = +25^\circ\text{C}$ ,  $V_S = +5\text{V}$ ,  $R_L = 10\text{k}\Omega$  connected to  $V_S/2$ ,  $V_{CM} = V_S/2$ , and  $V_{O_{UT}} = V_S/2$ , unless otherwise noted.

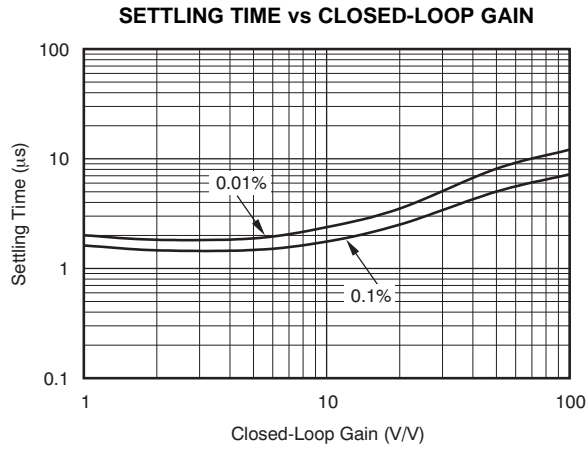


Figure 19.

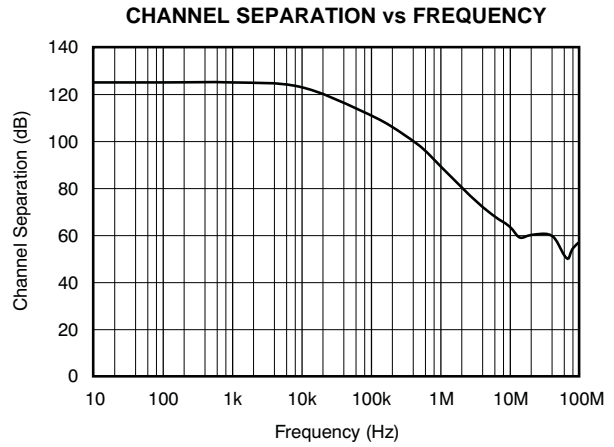


Figure 20.

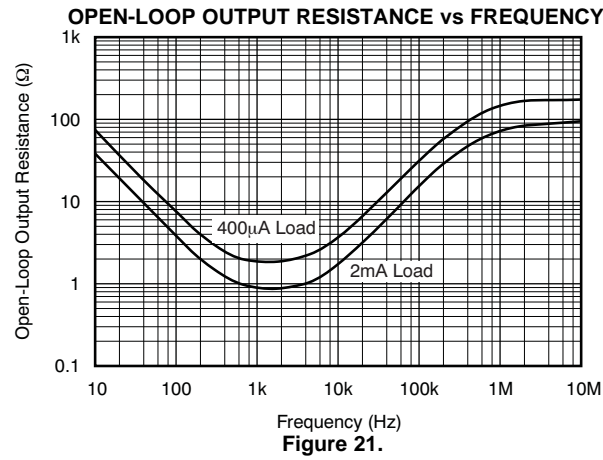


Figure 21.

## APPLICATION INFORMATION

The OPA376-Q1 family of operational amplifiers is built using *e-trim*, a proprietary technique in which offset voltage is adjusted during the final steps of manufacturing. This technique compensates for performance shifts that can occur during the molding process. Through *e-trim*, the OPA376-Q1 family delivers excellent offset voltage (5 $\mu$ V, typ). Additionally, the amplifier boasts a fast slew rate, low drift, low noise, and excellent PSRR and  $A_{OL}$ . These 5.5MHz CMOS op amps operate on 760 $\mu$ A (typ) quiescent current.

### OPERATING CHARACTERISTICS

The OPA376-Q1 family of amplifiers has parameters that are fully specified from 2.2V to 5.5V ( $\pm 1.1$ V to  $\pm 2.75$ V). Many of the specifications apply from  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in the [Typical Characteristics](#).

### GENERAL LAYOUT GUIDELINES

For best operational performance of the device, good printed circuit board (PCB) layout practices are required. Low-loss, 0.1 $\mu$ F bypass capacitors must be connected between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from  $V+$  to ground is applicable to single-supply applications.

### BASIC AMPLIFIER CONFIGURATIONS

The OPA376-Q1 family is unity-gain stable. It does not exhibit output phase inversion when the input is overdriven. A typical single-supply connection is shown in [Figure 22](#). The OPA376-Q1 is configured as a basic inverting amplifier with a gain of  $-10\text{V/V}$ . This single-supply connection has an output centered on the common-mode voltage,  $V_{CM}$ . For the circuit shown, this voltage is 2.5V, but may be any value within the common-mode input voltage range.

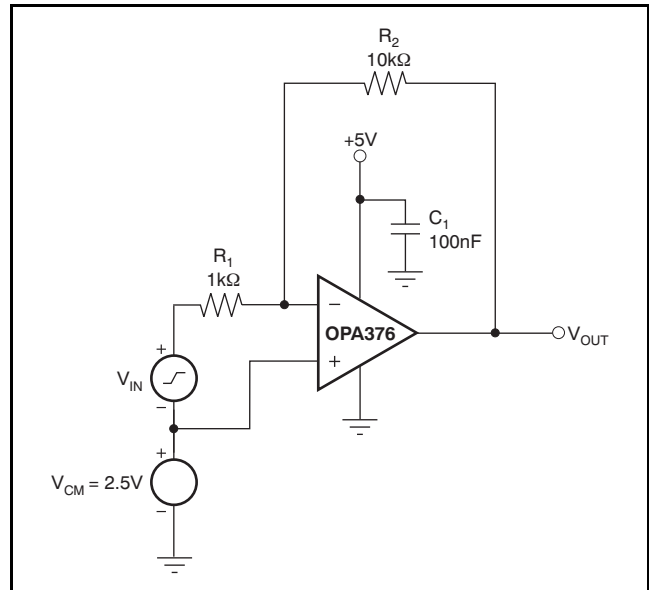


Figure 22. Basic Single-Supply Connection

### COMMON-MODE VOLTAGE RANGE

The input common-mode voltage range of the OPA376-Q1 series extends 100mV beyond the supply rails. The offset voltage of the amplifier is very low, from approximately  $(V-)$  to  $(V+) - 1\text{V}$ , as shown in [Figure 23](#). The offset voltage increases as common-mode voltage exceeds  $(V+) - 1\text{V}$ . Common-mode rejection is specified from  $(V-)$  to  $(V+) - 1.3\text{V}$ .

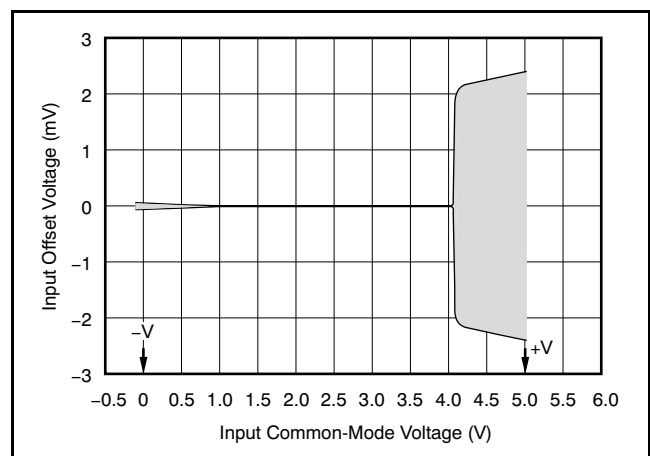


Figure 23. Offset and Common-Mode Voltage

## INPUT AND ESD PROTECTION

The OPA376-Q1 family incorporates internal electrostatic discharge (ESD) protection circuits on all pins. In the case of input and output pins, this protection primarily consists of current steering diodes connected between the input and power-supply pins. These ESD protection diodes also provide in-circuit, input overdrive protection, as long as the current is limited to 10mA as stated in the [Absolute Maximum Ratings](#). Figure 24 shows how a series input resistor may be added to the driven input to limit the input current. The added resistor contributes thermal noise at the amplifier input and its value should be kept to a minimum in noise-sensitive applications.

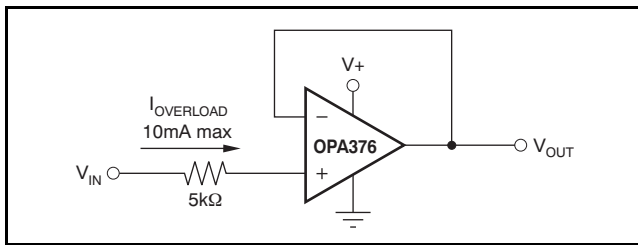


Figure 24. Input Current Protection

## CAPACITIVE LOAD AND STABILITY

The OPA376-Q1 series of amplifiers may be used in applications where driving a capacitive load is required. As with all op amps, there may be specific instances where the OPAx376 can become unstable, leading to oscillation. The particular op amp circuit configuration, layout, gain, and output loading are some of the factors to consider when establishing whether an amplifier will be stable in operation. An op amp in the unity-gain (+1V/V) buffer configuration and driving a capacitive load exhibits a greater tendency to be unstable than an amplifier operated at a higher noise gain. The capacitive load, in conjunction with the op amp output resistance, creates a pole within the feedback loop that degrades the phase margin. The degradation of the phase margin increases as the capacitive loading increases.

The OPAx376 in a unity-gain configuration can directly drive up to 250pF pure capacitive load. Increasing the gain enhances the ability of the amplifier to drive greater capacitive loads; see the typical characteristic plot, [Small-Signal Overshoot vs Capacitive Load](#). In unity-gain configurations, capacitive load drive can be improved by inserting a small (10Ω to 20Ω) resistor,  $R_S$ , in series with the output, as shown in Figure 25. This resistor significantly reduces ringing while maintaining dc performance for purely capacitive loads. However, if there is a resistive load in parallel with the capacitive

load, a voltage divider is created, introducing a gain error at the output and slightly reducing the output swing. The error introduced is proportional to the ratio  $R_S/R_L$ , and is generally negligible at low output current levels.

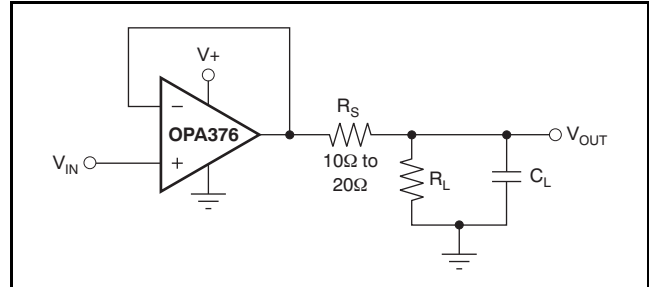


Figure 25. Improving Capacitive Load Drive

## ACTIVE FILTERING

The OPA376-Q1 series is well-suited for filter applications requiring a wide bandwidth, fast slew rate, low-noise, single-supply operational amplifier. Figure 26 shows a 50kHz, 2nd-order, low-pass filter. The components have been selected to provide a maximally-flat Butterworth response. Beyond the cutoff frequency, roll-off is -40dB/dec. The Butterworth response is ideal for applications requiring predictable gain characteristics such as the anti-aliasing filter used ahead of an analog-to-digital converter (ADC).

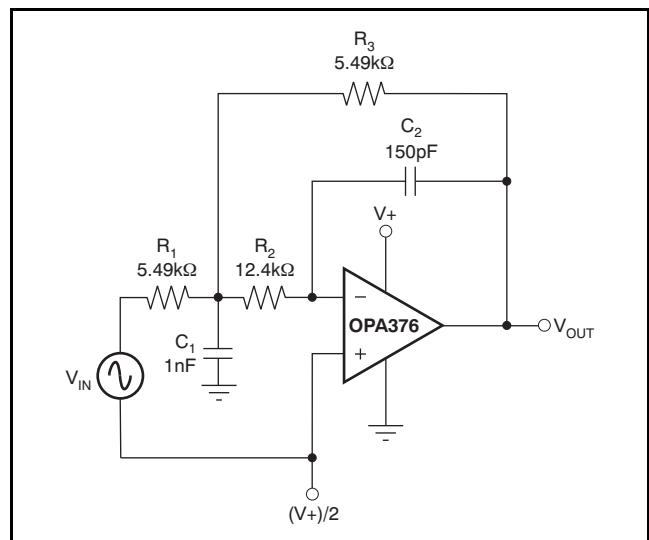


Figure 26. Second-Order Butterworth 50kHz Low-Pass Filter

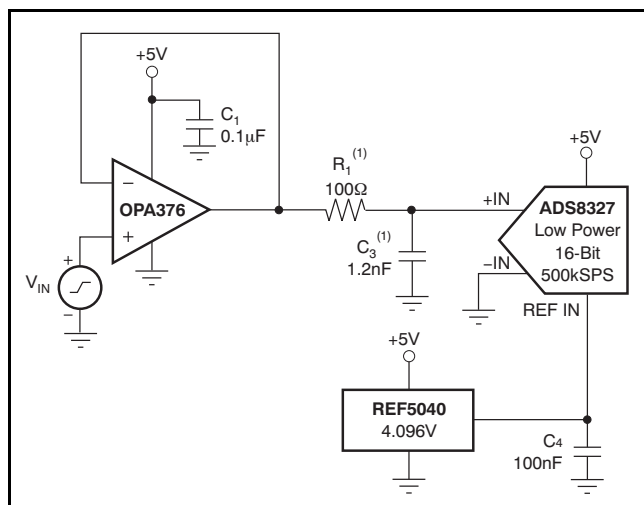
## PHOTOSENSITIVITY

Although the OPA2376YZD package has a protective backside coating that reduces the amount of light exposure on the die, unless fully shielded, ambient light can reach the active region of the device. Input

bias current for the package is specified in the absence of light. Depending on the amount of light exposure in a given application, an increase in bias current, and possible increases in offset voltage should be expected. Fluorescent lighting may introduce noise or hum because of the time-varying light output. Best layout practices include end-product packaging that provides shielding from possible light sources during operation.

### DRIVING AN ANALOG-TO-DIGITAL CONVERTER

The low noise and wide gain bandwidth of the OPA376-Q1 family make it an ideal driver for ADCs. Figure 27 illustrates the OPA376-Q1 driving an ADS8327, 16-bit, 250kSPS converter. The amplifier is connected as a unity-gain, noninverting buffer.



NOTE: (1) Suggested value; may require adjustment based on specific application.

Figure 27. Driving an ADS8327

### PHANTOM-POWERED MICROPHONE

The circuit shown in Figure 28 depicts how a remote microphone amplifier can be powered by a phantom source on the output side of the signal cable. The cable serves double duty, carrying both the differential output signal from and dc power to the microphone amplifier stage.

An OPA2376-Q1 serves as a single-ended input to a differential output amplifier with a 6dB gain. Common-mode bias for the two op amps is provided by the dc voltage developed across the electret microphone element. A 48V phantom supply is reduced to 5.1V by the series 6.8kΩ resistors on the output side of the cable, and the 4.7kΩ and zener diode on the input side of the cable. AC coupling blocks the different dc voltage levels from each other on each end of the cable.

An **INA163** instrumentation amplifier provides differential inputs and receives the balanced audio signals from the cable.

The **INA163** gain may be set from 0dB to 80dB by selecting the  $R_G$  value. The **INA163** circuit is typical of the input circuitry used in mixing consoles.

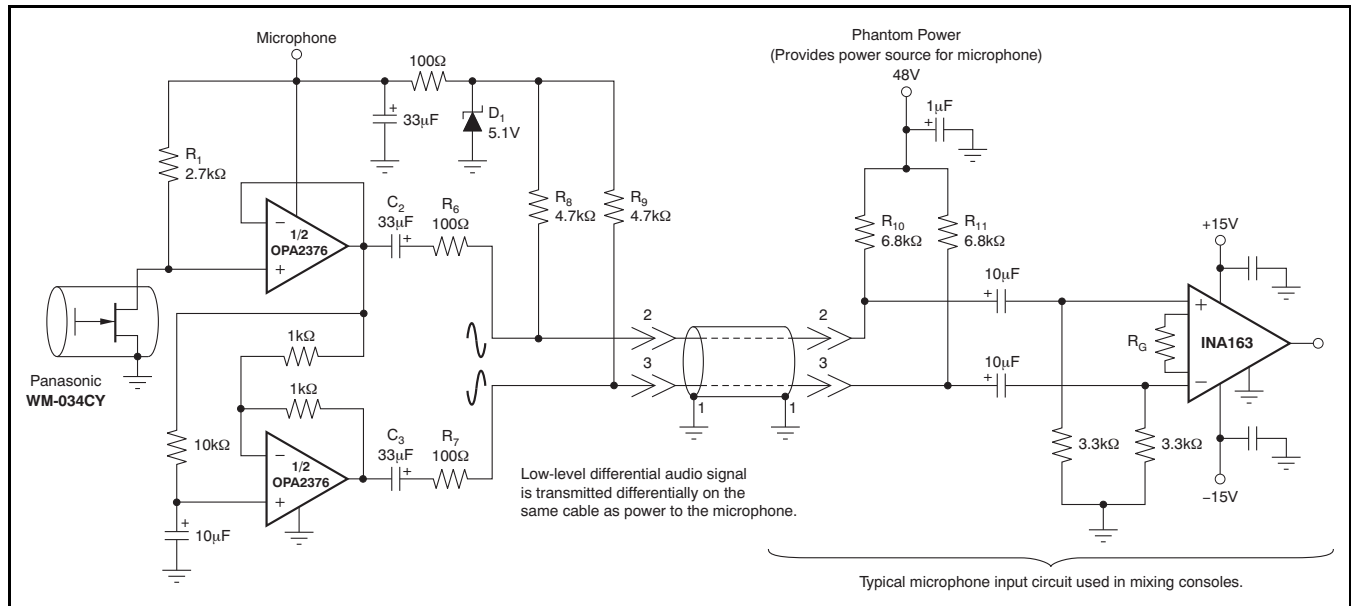
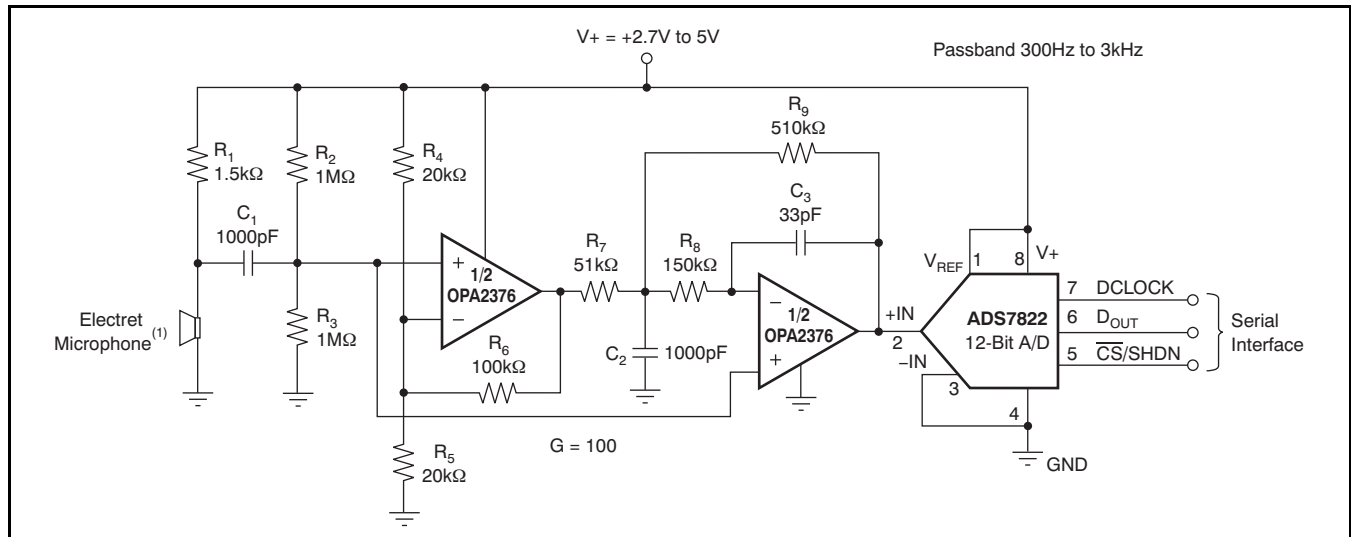


Figure 28. Phantom-Powered Electret Microphone



NOTE: (1) Electret microphone powered by  $R_1$ .

Figure 29. OPA2376-Q1 as a Speech Bandpass Filtered Data Acquisition System

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
TXS4555RGTR	ACTIVE	QFN	RGT	16	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	
TXS4555RUTR	ACTIVE	UQFN	RUT	12	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

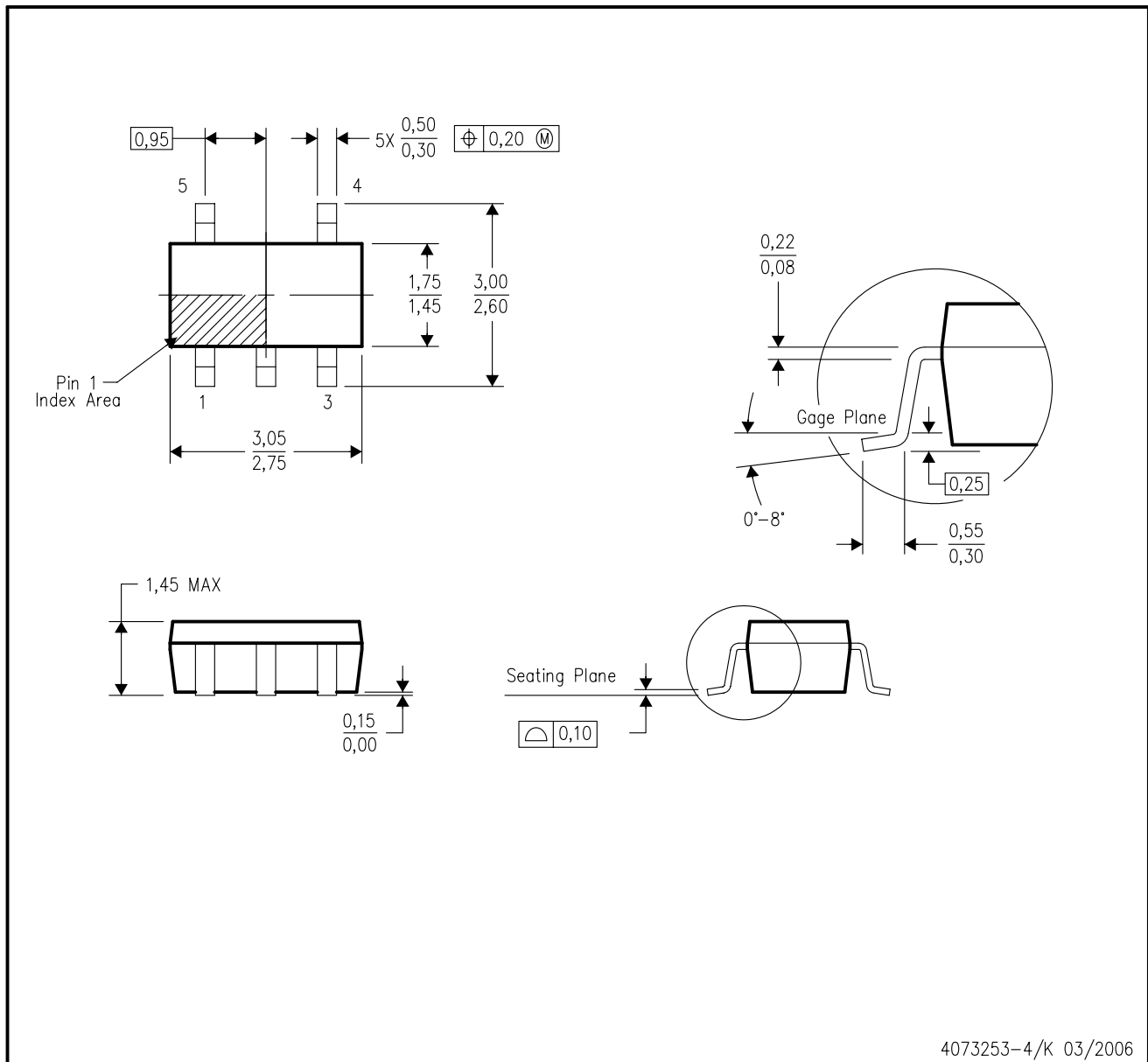
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-178 Variation AA.

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时钟和计时器	<a href="http://www.ti.com.cn/clockandtimers">http://www.ti.com.cn/clockandtimers</a>	医疗电子	<a href="http://www.ti.com.cn/medical">www.ti.com.cn/medical</a>
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电源管理	<a href="http://www.ti.com.cn/power">http://www.ti.com.cn/power</a>	视频和影像	<a href="http://www.ti.com.cn/video">www.ti.com.cn/video</a>
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